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#6/response
Dkny
PATENT 5-1-03
(PBM00026)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Li, et al.

§ Group Art Unit: 2822
§ Examiner: Lewis, M.

Serial No. 09/849,047

Atty. Dkt. No. 5298-04500

Filed: May 4, 2001

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date indicated below:

For: BURIED LAYER SUBSTRATE
ISOLATION IN INTEGRATED
CIRCUITS

April 23, 2003
Date

Pamela Gerik
Pamela Gerik

RESPONSE TO OFFICE ACTION MAILED JANUARY 31, 2003

Commissioner for Patents
Washington, D.C. 20231

Dear Madame:

This paper is submitted in response to the Office Action mailed January 31, 2003 to further highlight reasons why the application is in condition for allowance.

Remarks/Arguments begin on page 2 of this paper.

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